

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT										
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hae-Won Lee</td> <td>07/12/2004</td> </tr> <tr> <td>Young-Keun Lee</td> <td>07/12/2004</td> </tr> <tr> <td>Hwan-Kyu Jung</td> <td>07/12/2004</td> </tr> <tr> <td>Tae-Won Park</td> <td>07/12/2004</td> </tr> </tbody> </table>		Name	Execution Date	Hae-Won Lee	07/12/2004	Young-Keun Lee	07/12/2004	Hwan-Kyu Jung	07/12/2004	Tae-Won Park	07/12/2004
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Hae-Won Lee	07/12/2004										
Young-Keun Lee	07/12/2004										
Hwan-Kyu Jung	07/12/2004										
Tae-Won Park	07/12/2004										
<b>RECEIVING PARTY DATA</b>											
<b>Name:</b>	SK CORPORATION										
<b>Street Address:</b>	99, Seorin-dong, Jongro-gu										
<b>City:</b>	Seoul										
<b>State/Country:</b>	KOREA, REPUBLIC OF										
<b>Postal Code:</b>	110-110										
<b>PROPERTY NUMBERS Total: 1</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>10900334</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	10900334						
Property Type	Number										
Application Number:	10900334										
<b>CORRESPONDENCE DATA</b>											
<b>Fax Number:</b>	(202)835-1755										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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<b>Address Line 4:</b>	Washington, DISTRICT OF COLUMBIA 20006										
<b>NAME OF SUBMITTER:</b>	Christopher W. Brody										
<b>Total Attachments: 1</b> source=12119-2 Assignment#page1.tif											

OP \$40.00 10900334

ASSIGNMENT

This is an Assignment of the following rights, title and interest:

- United States of America rights, title and interest in the invention
- United States Patent Application Serial No. \_\_\_\_\_

Title of the Invention:

THERMOPLASTIC ELASTOMER COMPOSITION AND METHOD FOR PREPARING THE SAME

Inventors (assignors):

LEE, Hae-Won : 109-802, Sejong Apt., Jeonmin-dong, Yuseong-gu, Daejeon 305-728, Republic of Korea  
 LEE, Young-Keun : 102-1205, Sejong Apt., Jeonmin-dong, Yuseong-gu, Daejeon 305-728, Republic of Korea  
 JUNG, Hwan-Kyu : 101, 295-5, Jeonmin-dong, Yuseong-gu, Daejeon 305-390, Republic of Korea  
 PARK, Tae-Won : 302-1603, Expo Apt., Jeonmin-dong, Yuseong-gu, Daejeon 305-761, Republic of Korea

Assignee:

SK CORPORATION : 99, Seorin-dong, Jongro-gu, Seoul 110-110, Republic of Korea

Whereas, we, the above-identified Inventors, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter referred to as "Invention");

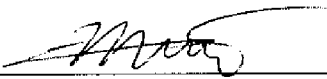
And, whereas we desire to assign our above-identified rights, title and interest in the Invention to the above-identified assignee;

Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged;

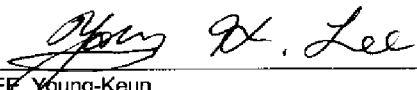
We hereby assign, sell and transfer our above-identified rights, title and interest in said Invention, said applications(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, which may be granted or have granted for said Invention, and in and to any and all reissues and reexaminations thereof, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States, unto said Assignee.

And we hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;

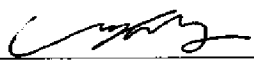
And we further agree to sign and execute all necessary and lawful future documents, including applications, for filing divisions, continuations and continuations-in-part of said application for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.

  
 \_\_\_\_\_  
 Signature: LEE, Hae-Won

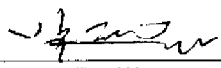
2004. 7. 12.  
 \_\_\_\_\_  
 Date

  
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 Signature: LEE, Young-Keun

July 12, 2004  
 \_\_\_\_\_  
 Date

  
 \_\_\_\_\_  
 Signature: JUNG, Hwan-Kyu

2004. 7. 12.  
 \_\_\_\_\_  
 Date

  
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 Signature: PARK, Tae-Won

2004. 7. 12  
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 Date

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